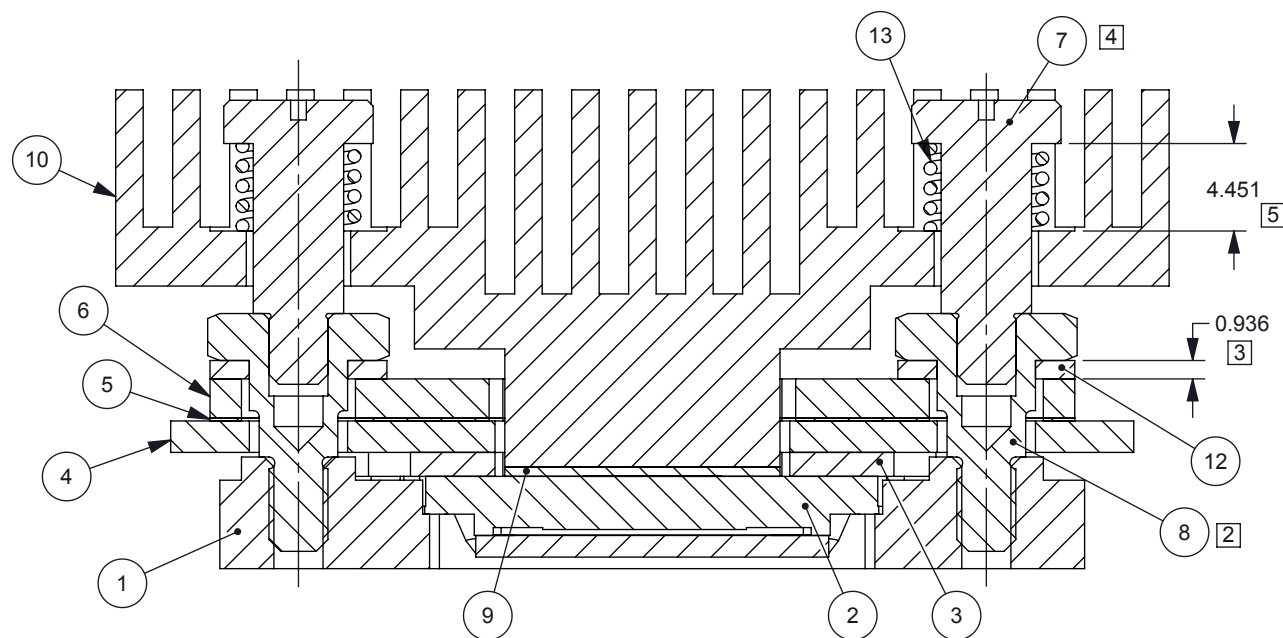
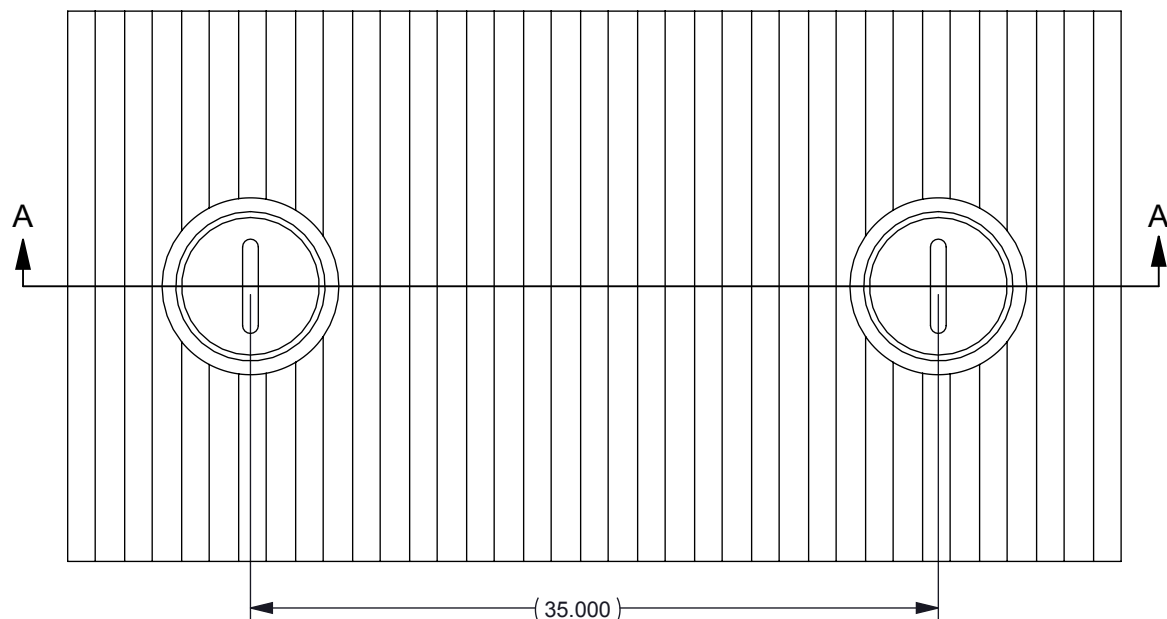
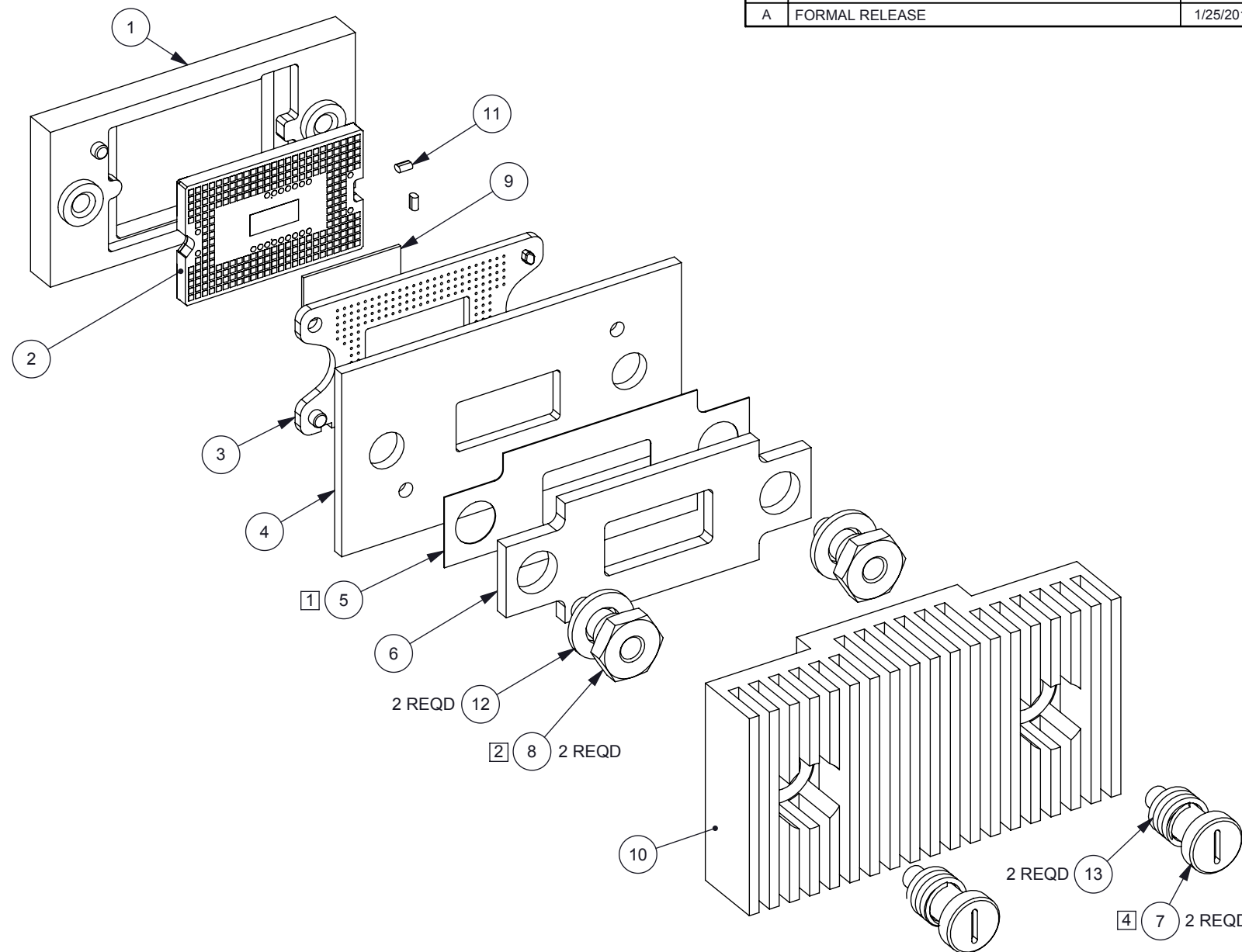



- 1 THE INSULATOR (ITEM 5) NEEDS TO BE OF SUFFICIENT THICKNESS TO ISOLATE THE PCB FROM THE METAL CLAMP (ITEM 6), TO KEEP IT FROM CAPACITIVELY COUPLING SIGNALS TOGETHER.
- 2 WHEN TIGHTENING STANDOFFS (ITEM 8 ) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOAD FOR THE ELECTRICAL AREA SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE STANDOFFS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREA.
- 3 CRITICAL GAP FOR COMPRESSION WASHER DESIGN TO CONTROL LOADS ON THE DMD ELECTRICAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES. THE RESULTING FORCE APPLIED BY THE COMPRESSION WASHER DEPENDS ON GAP SIZE AND WASHER MATERIAL PROPERTIES.
- 4 WHEN TIGHTENING SCREWS (ITEM 7) BE SURE CLAMPING FORCES DO NOT EXCEED THE MAXIMUM LOADS FOR THE THERMAL AREA SPECIFIED IN THE DMD DATA SHEET. CARE SHOULD BE TAKEN AS THE SCREWS ARE TIGHTENED TO MAINTAIN A UNIFORM LOAD ACROSS THE AREA.
- 5 CRITICAL GAP FOR COIL SPRING DESIGN TO CONTROL LOADS ON THE DMD THERMAL INTERFACE AREA. THE SIZE OF THE GAP WILL VARY DEPENDING ON PART TOLERANCES AND SPRING PROPERTIES.



SECTION A-A



2	13	LEE SPRING LC 026CD 01S	COIL SPRING	
2	12	2515399	WASHER, COMPRESSION	
2	11	2512939	SHIM, FOAM ALIGNMENT	
1	10	2515389	HEAT SINK SERIES 316	
1	9	2515390	THERMAL PAD	
2	8	2515398	STANDOFF	
2	7	2515396	SCREW, SHOULDER, CONCEPT #1	
1	6	2515392	CLAMP, SERIES 316	
1	5	2515395	PCB INSULATOR, SERIES 316	
1	4	2515393	PCB, OUTLINE SERIES 316	
1	3	2515386	INTERPOSER, 1080P SERIES 316	
1	2		DMD, SERIES 316	
1	1	2515388	INTERFACE, SERIES 316	
QTY	ITEM	PART NUMBER	DESCRIPTION	Notes

		<p><b>UNLESS OTHERWISE SPECIFIED</b></p> <ul style="list-style-type: none"> <li>● DIMENSIONS ARE IN MILLIMETERS</li> <li>● TOLERANCES: ANGLES <math>\pm 1^\circ</math> 2 PLACE DECIMALS <math>\pm 0.25</math> 1 PLACE DECIMALS <math>\pm 0.50</math></li> <li>● DIMENSIONAL LIMITS APPLY BEFORE PROCESSES</li> <li>● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994</li> <li>● REMOVE ALL BURRS AND SHARP EDGES</li> <li>● PARENTHETICAL INFO FOR REF ONLY</li> </ul>		<p>DWN J. McKinLEY</p> <p>DATE</p>		 <p>TEXAS INSTRUMENTS</p>	
				<p>Engr</p>			
				<p>CQE/QA</p>		<p><b>ASSEMBLY, SERIES 316 DMD MOUNTING CONCEPT</b></p>	
				<p>CM</p>			
<p>NONE      0314RD</p>				<p>SIZE B</p>		<p>DWG NO 2515387</p>	<p>REV A</p>
<p>NEXT ASSY      USED ON</p>		<p>Apprvd McKinLEY</p>		<p>1/25/2017</p>	<p>SCALE 2:1</p>	<p>SHEET 1 OF 2</p>	
<p>APPLICATION</p>							

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SSZZ031 January 01, 2013



DWN  
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DATE \_\_\_\_\_

SIZE	B
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DRAWING NO  
2515387-Assembly

REV  
A

SCALE 2:1

SHEET 2 OF 2